

20V Common-Drain Dual N-Channel MOSFET

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent R_{DS(ON)}
- High Power and Current Handling Capability
- Green Device Available

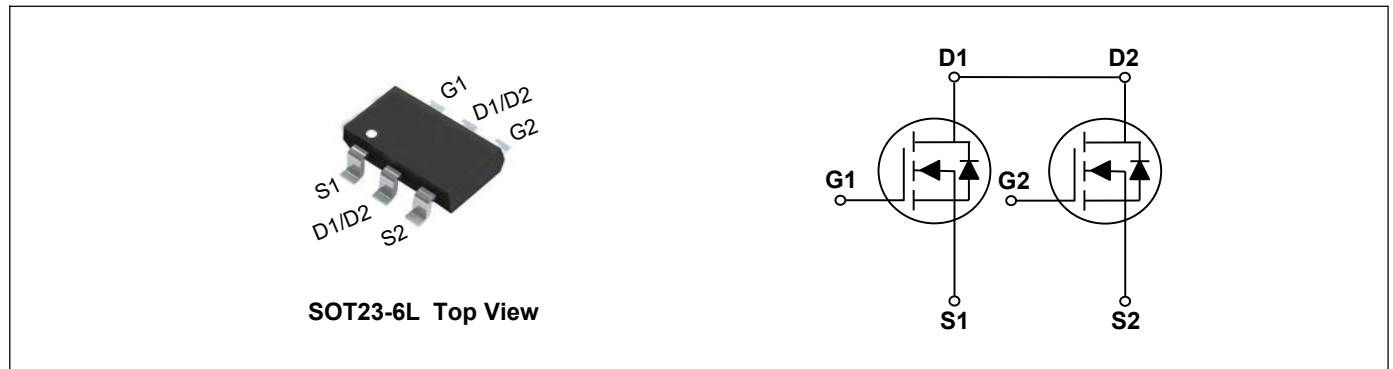
Applications

- High Frequency Point-of-Load, Synchronous Buck Converter
- Battery Protection, Power Management
- Load Switch

Product Summary



V _{DS}	20	V
I _D	6	A
R _{DS(ON)} (at V _{GS} =4.5V)	25	mΩ
R _{DS(ON)} (at V _{GS} =2.5V)	32	mΩ



Absolute Maximum Ratings(T_A=25°C, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±10	V
Continuous Drain Current	I _D	6	A
Pulsed Drain Current ²	I _{DM}	25	A
Total Power Dissipation ³	P _D	1.25	W
Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction Temperature Range	T _J	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient ¹	R _{θJA}	---	357	°C/W

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Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20	---	---	V
Static Drain-Source On-Resistance ²	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=6A$	---	---	25	m Ω
		$V_{GS}=2.5V, I_D=5A$	---	---	32	m Ω
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	0.5	---	0.9	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=18V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 10V, V_{DS}=0V$	---	---	± 100	nA
Forward Transconductance	g_{fs}	$V_{DS}=5V, I_D=4.5A$	---	10	---	S
Total Gate Charge	Q_g	$V_{DS}=10V, V_{GS}=4.5V, I_D=4A$	---	11	---	nC
Gate-Source Charge	Q_{gs}		---	2.3	---	
Gate-Drain Charge	Q_{gd}		---	2.5	---	
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=10V, V_{GS}=4V, R_G=10\Omega, I_D=1A$	---	18	---	ns
Rise Time	T_r		---	5	---	
Turn-Off Delay Time	$T_{d(off)}$		---	43	---	
Fall Time	T_f		---	20	---	
Input Capacitance	C_{iss}	$V_{DS}=8V, V_{GS}=0V, f=1\text{MHz}$	---	800	---	pF
Output Capacitance	C_{oss}		---	155	---	
Reverse Transfer Capacitance	C_{rss}		---	125	---	

Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Diode Forward Voltage ²	V_{SD}	$V_{GS}=0V, I_S=1.25A, T_J=25^\circ\text{C}$	---	---	1.2	V

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150 $^\circ\text{C}$ junction temperature

Typical Characteristics

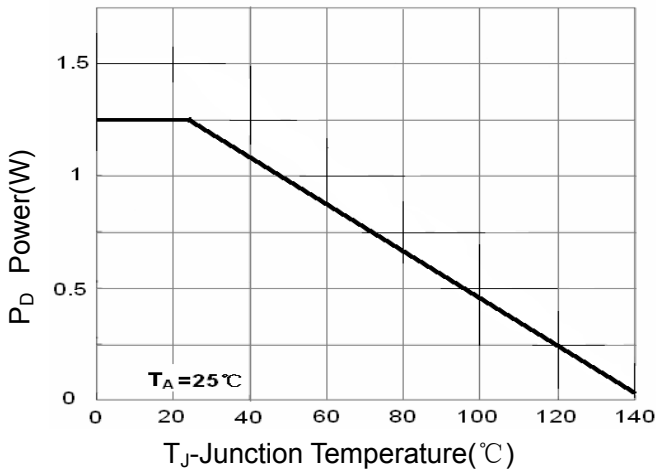


Figure 1 Power Dissipation

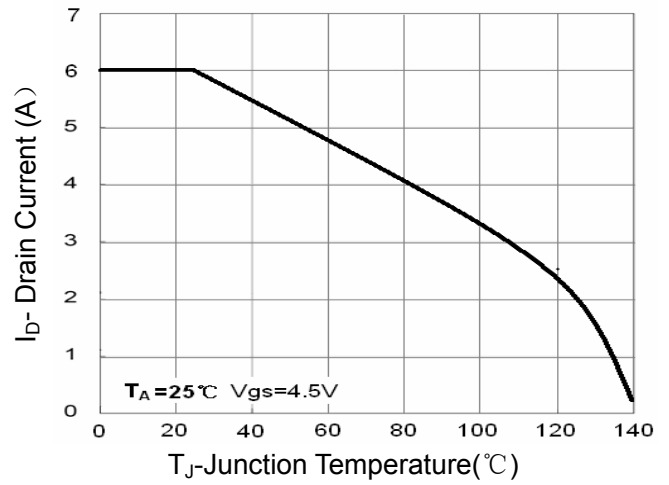


Figure 2 Drain Current

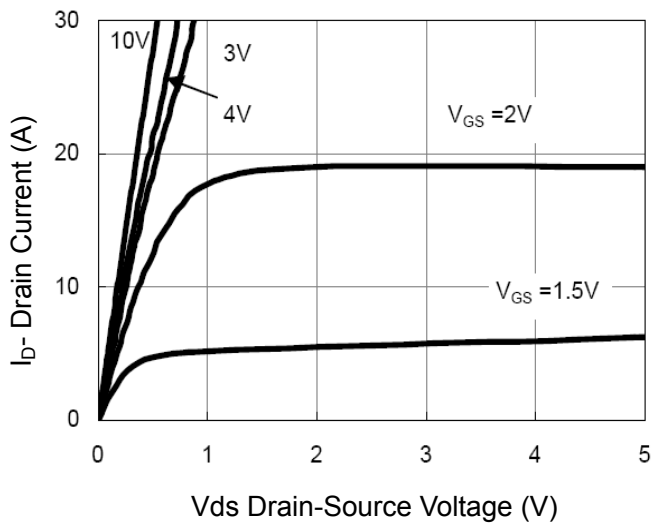


Figure 3 Output Characteristics

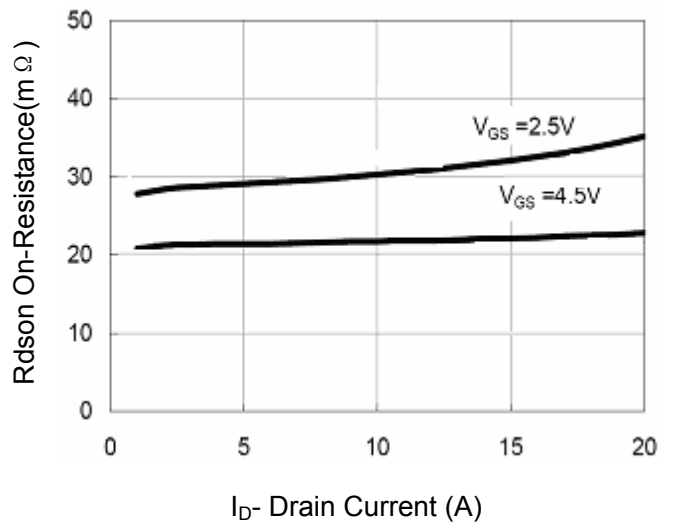


Figure 4 Drain-Source On-Resistance

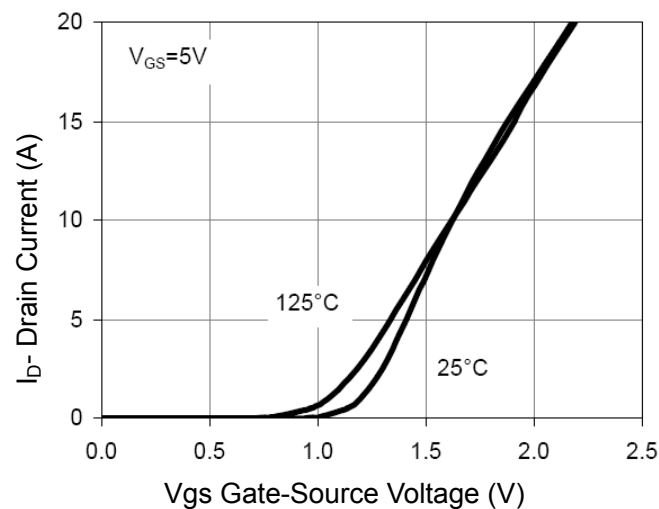


Figure 5 Transfer Characteristics

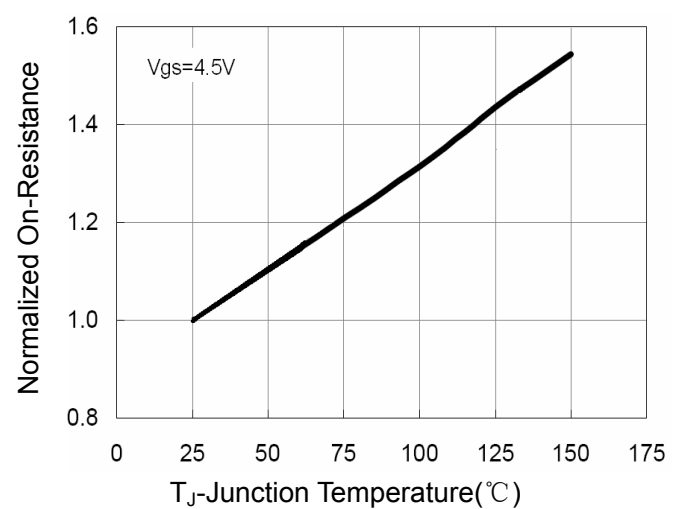
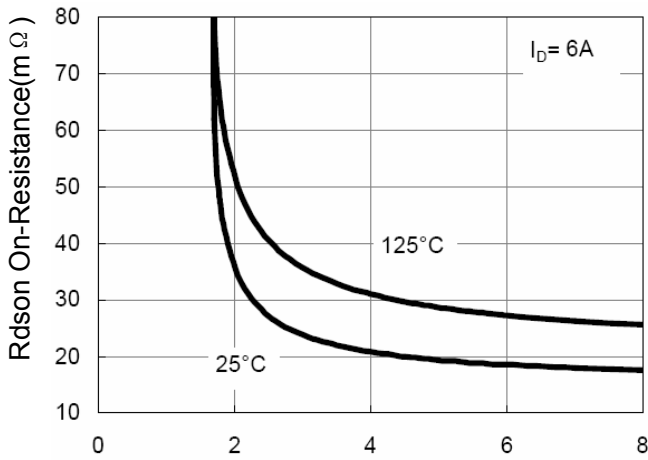
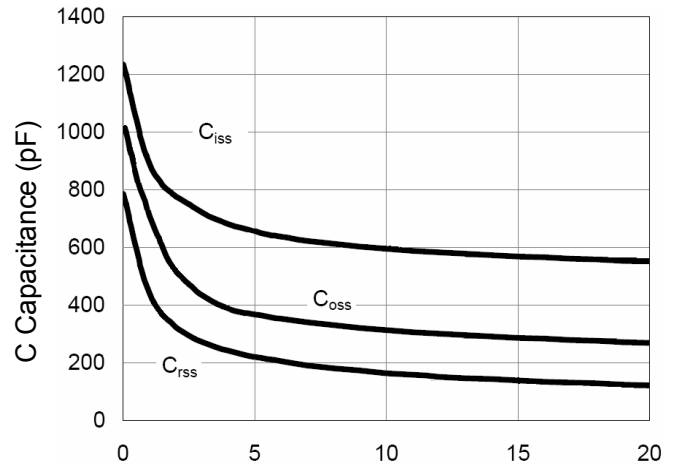


Figure 6 Drain-Source On-Resistance

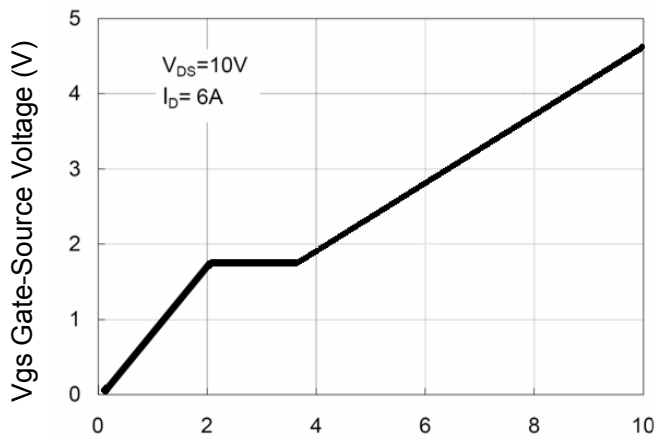
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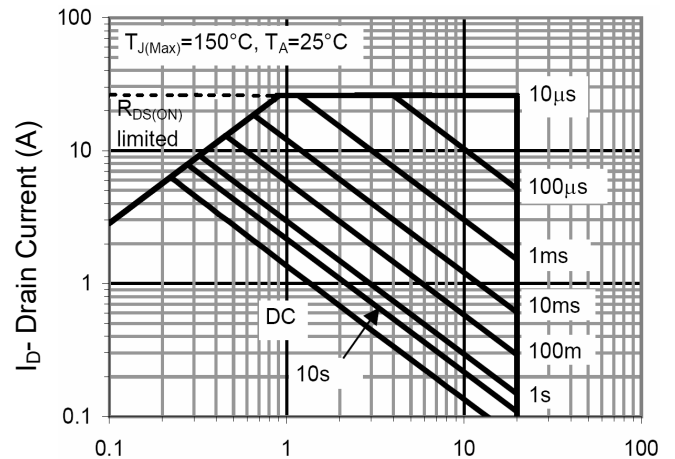
Vgs Gate-Source Voltage (V)
Figure 7 Rdson vs Vgs



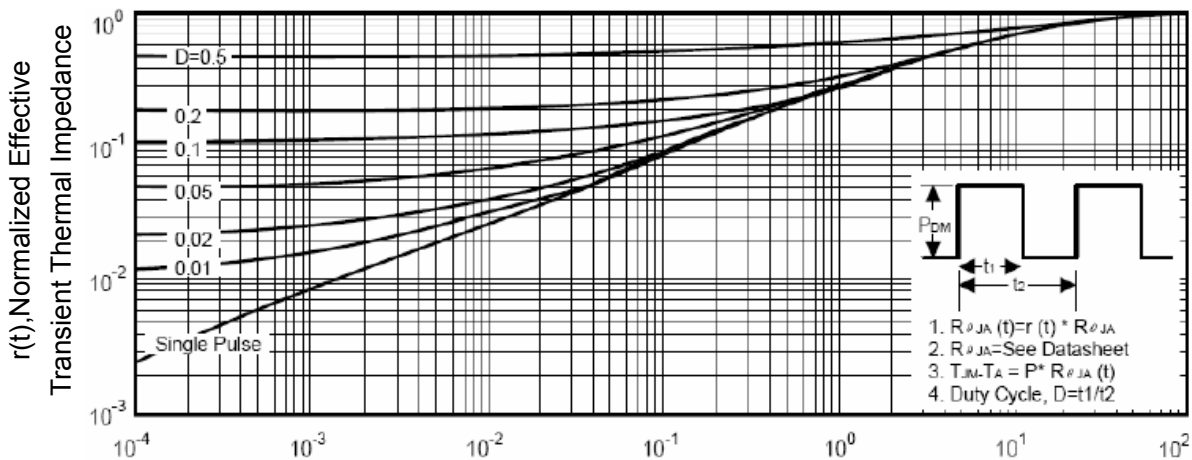
Vds Drain-Source Voltage (V)
Figure 8 Capacitance vs Vds



Qg Gate Charge (nC)
Figure 9 Gate Charge



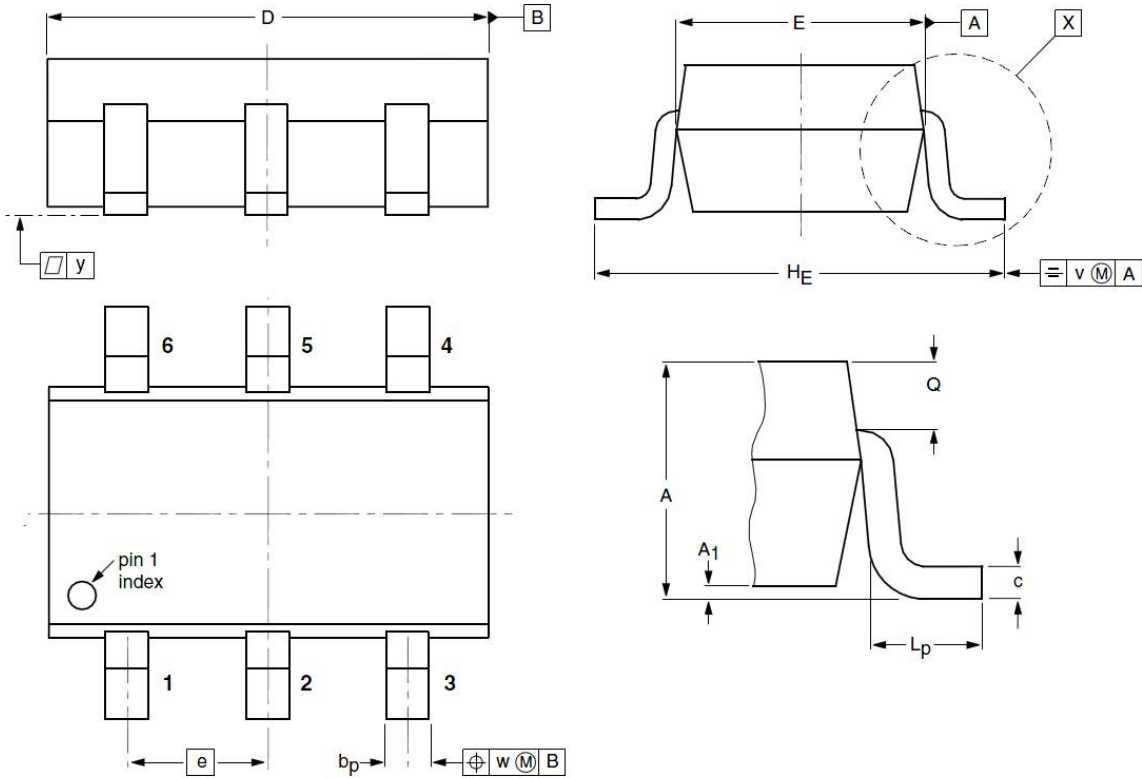
Vds Drain-Source Voltage (V)
Figure 10 Safe Operation Area



Square Wave Pulse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance

SOT23-6L Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.90	1.07	1.45	A₁	0.01	0.05	0.15
b_p	0.30	0.40	0.50	c	0.10	0.15	0.22
D	2.70	2.92	3.10	E	1.35	1.55	1.75
e	--	0.95	--	H_E	2.50	2.80	3.00
L_p	0.30	0.45	0.60	Q	0.23	0.29	0.33
v	--	0.20	--	W	--	0.20	--
y	--	0.10	--				